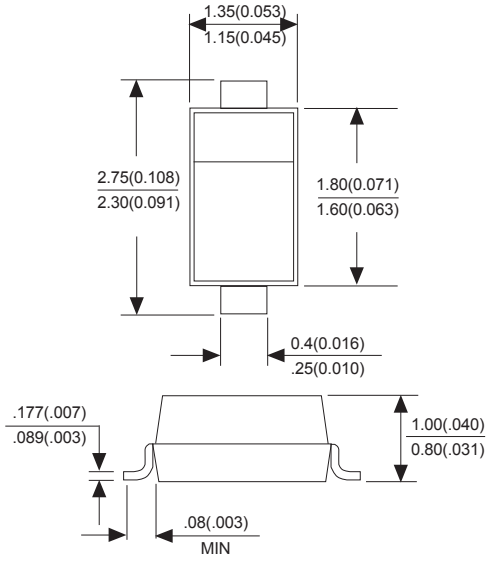
B5819WS

Surface Mount Schottky Barrier Rectifiers

SOD-323



Dimensions in millimeters and (inches)

FEATURES

Glass passivated device

Ideal for surface mouted applications

Low reverse leakage

Metallurgically bonded construction

High temperature soldering guaranteed:

MECHANICAL DATA

Case:SOD-323 molded plastic body over passivated chip

Terminals: Plated axial leads, solderable per MIL-STD-750, Method 2026

Polarity: Color band denotes cathode end

Mounting Position: Any

Mraking: SL

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25 C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz,resistive or inductive load,for capacitive load current derate by 20%.

	SYMBOLS	B5819WS	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	40	V
Maximum RMS voltage	V_{RMS}	28	V
Maximum DC blocking voltage	V_{DC}	40	V
Maximum average forward rectified current	$I_{(AV)}$	1.0	A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	9.0	A
Maximum instantaneous forward voltage at 1.0A	V_F	0.55	V
Maximum DC reverse current T_A=25℃	I_R	0.05	mA
at rated DC blocking voltage T_A=100℃		1.0	
Typical junction capacitance	C_J	120	pF
Typical thermal resistance	$R_{\theta JA}$	400	°C/W
Power Dissipation	PD	250	mW
Storage temperature range	T_{STG}	-55 to +150	°C

Note:1.Measured at 1MHz and applied reverse voltage of 4.0V D.C.

FIG. 1- FORWARD CURRENT DERATING CURVE

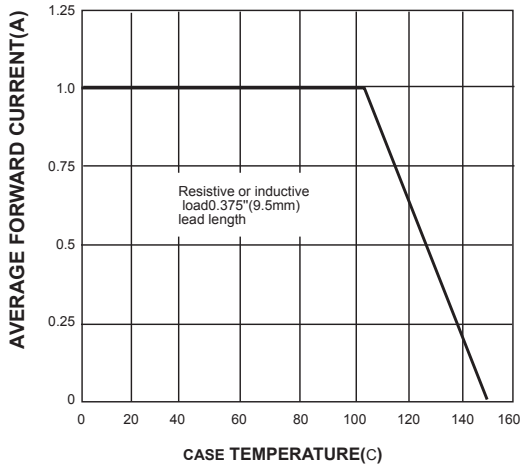


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

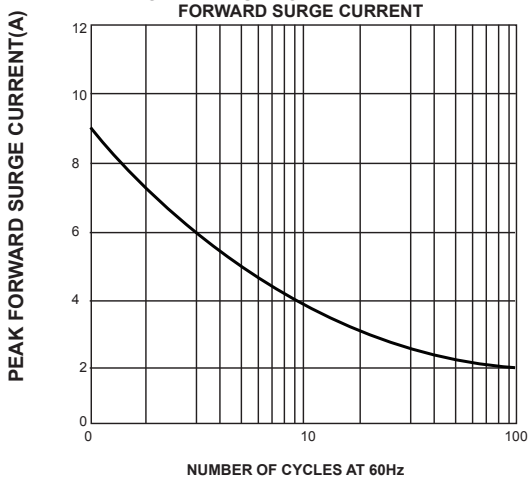


FIG. 3- TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

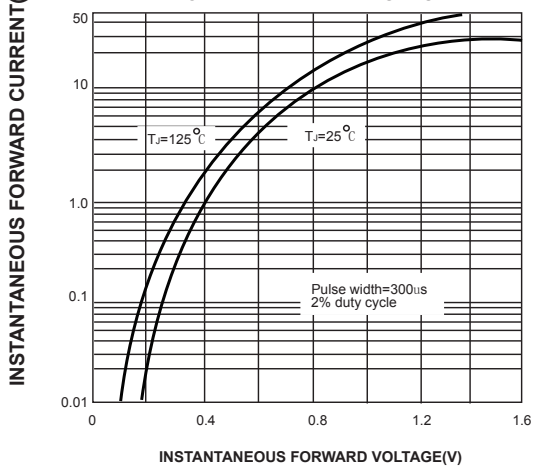


FIG. 4- TYPICAL REVERSE CHARACTERISTICS

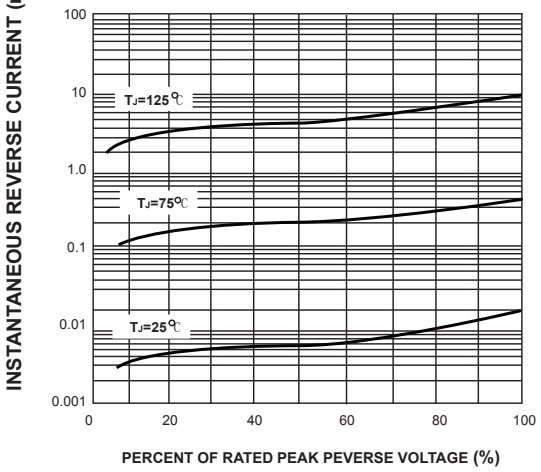


FIG. 5- TYPICAL JUNCTION CAPACITANCE

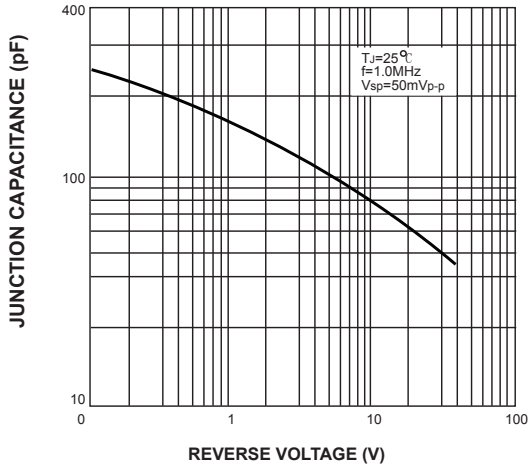


FIG. 6-TYPICAL TRANSIENT THERMAL IMPEDANCE